

REMARKS

Claims 9-22 are pending in this application. By this Amendment, claims 1-8 are canceled, and new claims 9-22 are added. Reconsideration of the application is respectfully requested.

The Office Action rejects claims 1-8 under 35 U.S.C. §103(a) over U.S. Patent 6,242,719 to Kano et al. in view of U.S. Patent 5,877,473 to Koontz. This rejection is moot with respect to the canceled claims 1-8, and is traversed with respect to claims 9-22, where applicable.

The Office Action admits that Kano does not disclose or suggest a bending portion having a curvature radius within the range of 0.1 mm to 20 mm. However, the Office Action asserts that Koontz discloses this feature. Applicant respectfully submits that Kano and Koontz, individually or in combination, do not disclose or suggest "a semiconductor wafer is heated on a surface opposite to the surface of the ceramic substrate forming the heat-generating body," as recited in claim 9.

Kano discloses a device having a heater pattern 3 on a surface of a substrate 2. See Figs. 1B and 3 and col. 4, lines 44-55. A semiconductor wafer W is located and heated on the same surface of the substrate 2 on which the heater pattern 3 resides, while feeding terminal 5 and feeding member 6 are located on the surface opposite to the surface of the substrate 2 on which the heater pattern 3 resides. See Fig. 3 and col. 5, lines 5-15. Thus, the semiconductor wafer W is not located or heated on the surface opposite to the surface of the substrate 2 on which the heater pattern 3 resides. Nowhere does Kano disclose or suggest locating or heating the semiconductor wafer W on the surface opposite to the surface of the substrate 2 on which the heater pattern 3 resides. Therefore, Kano does not disclose or suggest "a semiconductor wafer is heated on a surface opposite to the surface of the ceramic substrate forming the heat-generating body," as recited in claim 9.

Koontz discloses vehicle windshields having heating elements. See col. 2, lines 44-56. Nowhere does Koontz disclose or suggest a semiconductor wafer that is heated on the surface opposite to the surface of a ceramic substrate forming a heat-generating body. Thus, Koontz does not supply the subject matter lacking in Kano. Accordingly, Kano and Koontz, individually or in combination, do not disclose or suggest the subject matter recited in claim 9, and claims 10-15 depending therefrom.

Furthermore, Applicant respectfully submits that Kano and Koontz, individually or in combination, do not disclose or suggest a heat-generation pattern disposed within a disk-shaped ceramic substrate, as recited in claim 16. As discussed above, Kano discloses a device having heater pattern 3 on the surface of the substrate 2. See Fig. 1B and col. 4, lines 44-55. The heater pattern 3 is not formed inside the substrate 2. Thus, the heater pattern 3 is not within the substrate 2. Nowhere does Kano disclose or suggest a heater pattern 3 that is within the substrate 2. Therefore, Kano does not disclose or suggest a heat-generation pattern disposed within a disk-shaped ceramic substrate, as recited in claim 16.

As discussed above, Koontz discloses vehicle windshields having heating elements. See col. 2, lines 44-56. The windshields have an outer glass sheet 22 and an inner glass sheet 24 joined by an interlayer 26 made of a sheet of polyvinylbutyral. See Fig. 2 and col. 3, lines 59-64. A heating element 42 is located between the outer glass sheet 22 and the polyvinylbutyral interlayer 26. See Fig. 2 and col. 4, lines 48-55. One side of the heating element 42 is in contact with the outer glass sheet 22, and the other side of the heating element 42 is in contact with the polyvinylbutyral interlayer 26. Thus, the heating element 42 is not formed within a substrate.

Koontz discloses a heating element 44 that includes a substrate 52 and a conducting member 54. See Fig. 3 and col. 6, lines 32-36. The conducting member 54 is on the surface of the substrate 52, and is not inside the substrate 52. Therefore, the conducting member 54 is not

formed within the substrate 52. Nowhere does Koontz disclose or suggest a heating element or a conducting member that is formed within a substrate.

For at least the above reasons, Koontz does not supply the subject matter lacking in Kano. Thus, Kano and Koontz, individually or in combination, do not disclose or suggest the subject matter recited in claim 16, and claims 17-22 depending therefrom.

In view of the above, withdrawal of the rejection of claims 1-8, and claims 9-22, where applicable, under 35 U.S.C. §103(a) is respectfully requested.

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 9-22 are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in better condition for allowance, the Examiner is invited to contact Applicant's undersigned representative at the telephone number listed below.

Respectfully submitted,



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